

THICK FILM CONDUCTIVE PASTE COMPOSITION

ABSTRACT OF INVENTION

This invention is directed to a thick film
5 conductive paste composition comprising conductive
paste, polymer binder and at least one organic additive
being selected from the group of amidosulfuric metallic
salt, higher fatty acid metallic salt and metal
resinate utilized for forming termination of chip
10 resistor without an occurrence of swelling and/or
cracks in the superimposed area of the termination and
resistor.

Figure 3